

# 74AUP1G79

Low-power D-type flip-flop; positive-edge trigger

Rev. 02 — 17 October 2006

Product data sheet

## 1. General description

The 74AUP1G79 is a high-performance, low-power, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

Schmitt trigger action at all inputs makes the circuit tolerant to slower input rise and fall times across the entire  $V_{CC}$  range from 0.8 V to 3.6 V.

This device ensures a very low static and dynamic power consumption across the entire  $V_{CC}$  range from 0.8 V to 3.6 V.

This device is fully specified for partial Power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

The 74AUP1G79 provides the single positive-edge triggered D-type flip-flop. Information on the data input is transferred to the Q output on the LOW-to-HIGH transition of the clock pulse. The D input must be stable one setup time prior to the LOW-to-HIGH clock transition for predictable operation.

## 2. Features

- Wide supply voltage range from 0.8 V to 3.6 V
- High noise immunity
- Complies with JEDEC standards:
  - ◆ JESD8-12 (0.8 V to 1.3 V)
  - ◆ JESD8-11 (0.9 V to 1.65 V)
  - ◆ JESD8-7 (1.2 V to 1.95 V)
  - ◆ JESD8-5 (1.8 V to 2.7 V)
  - ◆ JESD8-B (2.7 V to 3.6 V)
- ESD protection:
  - ◆ HBM JESD22-A114-D Class 3A exceeds 5000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
  - ◆ CDM JESD22-C101-C exceeds 1000 V
- Low static power consumption;  $I_{CC} = 0.9 \mu\text{A}$  (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot < 10 % of  $V_{CC}$
- $I_{OFF}$  circuitry provides partial Power-down mode operation
- Multiple package options
- Specified from  $-40 \text{ }^\circ\text{C}$  to  $+85 \text{ }^\circ\text{C}$  and  $-40 \text{ }^\circ\text{C}$  to  $+125 \text{ }^\circ\text{C}$

### 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74AUP1G79GW	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74AUP1G79GM	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886
74AUP1G79GF	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm	SOT891

### 4. Marking

Table 2. Marking

Type number	Marking code
74AUP1G79GW	pP
74AUP1G79GM	pP
74AUP1G79GF	pP

### 5. Functional diagram

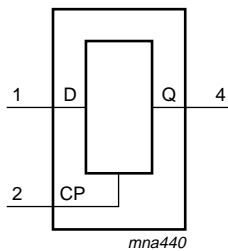


Fig 1. Logic symbol

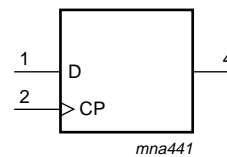


Fig 2. IEC logic symbol

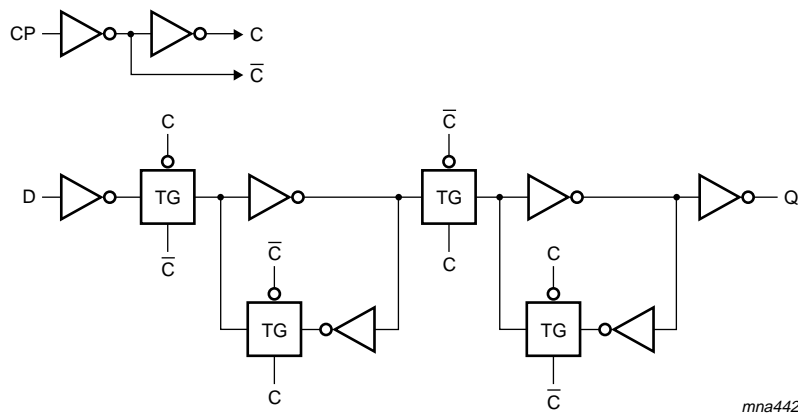


Fig 3. Logic diagram

## 6. Pinning information

### 6.1 Pinning

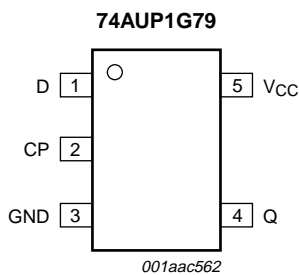


Fig 4. Pin configuration SOT353-1 (TSSOP5)

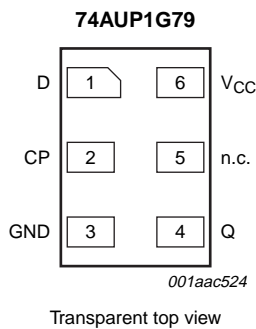


Fig 5. Pin configuration SOT886 (XSON6)

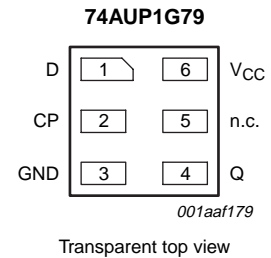


Fig 6. Pin configuration SOT891 (XSON6)

### 6.2 Pin description

Table 3. Pin description

Symbol	Pin		Description
	TSSOP5	XSON6	
D	1	1	data input D
CP	2	2	clock pulse input CP
GND	3	3	ground (0 V)
Q	4	4	data output Q
n.c.	-	5	not connected
V <sub>CC</sub>	5	6	supply voltage

## 7. Functional description

Table 4. Function table<sup>[1]</sup>

Input		Output
CP	D	Q
↑	L	L
↑	H	H
L	X	q

- [1] H = HIGH voltage level;  
 L = LOW voltage level;  
 ↑ = LOW-to-HIGH CP transition;  
 X = don't care;  
 q = lower case letter indicates the state of referenced input, one setup time prior to the LOW-to-HIGH CP transition.

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+4.6	V
$I_{IK}$	input clamping current	$V_I < 0$ V	-	-50	mA
$V_I$	input voltage		[1] -0.5	+4.6	V
$I_{OK}$	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	±50	mA
$V_O$	output voltage	Active mode and Power-down mode	[1] -0.5	+4.6	V
$I_O$	output current	$V_O = 0$ V to $V_{CC}$	-	±20	mA
$I_{CC}$	supply current		-	50	mA
$I_{GND}$	ground current		-	-50	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[2] -	250	mW

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 [2] For TSSOP5 packages: above 87.5 °C the value of  $P_{tot}$  derates linearly with 4.0 mW/K.  
 For XSON6 packages: above 45 °C the value of  $P_{tot}$  derates linearly with 2.4 mW/K.

## 9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		0.8	3.6	V
$V_I$	input voltage		0	3.6	V
$V_O$	output voltage	Active mode	0	$V_{CC}$	V
		Power-down mode; $V_{CC} = 0$ V	0	3.6	V
$T_{amb}$	ambient temperature		-40	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 0.8$ V to 3.6 V	0	200	ns/V

## 10. Static characteristics

**Table 7. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>T<sub>amb</sub> = 25 °C</b>						
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 0.8 V	0.70 × V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	0.65 × V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	-	-	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 0.8 V	-	-	0.30 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	-	-	0.35 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>				
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	V <sub>CC</sub> - 0.1	-	-	V
		I <sub>O</sub> = -1.1 mA; V <sub>CC</sub> = 1.1 V	0.75 × V <sub>CC</sub>	-	-	V
		I <sub>O</sub> = -1.7 mA; V <sub>CC</sub> = 1.4 V	1.11	-	-	V
		I <sub>O</sub> = -1.9 mA; V <sub>CC</sub> = 1.65 V	1.32	-	-	V
		I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 2.3 V	2.05	-	-	V
		I <sub>O</sub> = -3.1 mA; V <sub>CC</sub> = 2.3 V	1.9	-	-	V
		I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V	2.72	-	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>				
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.1	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	0.3 × V <sub>CC</sub>	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.31	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.31	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.31	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.44	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.31	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = GND to 3.6 V; V <sub>CC</sub> = 0 V to 3.6 V	-	-	±0.1	μA
	I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-	±0.2
ΔI <sub>OFF</sub>	additional power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V to 0.2 V	-	-	±0.2	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = GND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.5	μA
ΔI <sub>CC</sub>	additional supply current	per pin; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 3.3 V	<a href="#">[1]</a>	-	40	μA
C <sub>I</sub>	input capacitance	V <sub>CC</sub> = 0 V to 3.6 V; V <sub>I</sub> = GND or V <sub>CC</sub>	-	0.8	-	pF
C <sub>O</sub>	output capacitance	V <sub>O</sub> = GND; V <sub>CC</sub> = 0 V	-	1.7	-	pF

**Table 7. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>T<sub>amb</sub> = -40 °C to +85 °C</b>						
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 0.8 V	0.70 × V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	0.65 × V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	-	-	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 0.8 V	-	-	0.30 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	-	-	0.35 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>				
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	V <sub>CC</sub> - 0.1	-	-	V
		I <sub>O</sub> = -1.1 mA; V <sub>CC</sub> = 1.1 V	0.7 × V <sub>CC</sub>	-	-	V
		I <sub>O</sub> = -1.7 mA; V <sub>CC</sub> = 1.4 V	1.03	-	-	V
		I <sub>O</sub> = -1.9 mA; V <sub>CC</sub> = 1.65 V	1.30	-	-	V
		I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 2.3 V	1.97	-	-	V
		I <sub>O</sub> = -3.1 mA; V <sub>CC</sub> = 2.3 V	1.85	-	-	V
		I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V	2.67	-	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>				
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.1	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	0.3 × V <sub>CC</sub>	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.37	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.35	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.33	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.45	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.33	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = GND to 3.6 V; V <sub>CC</sub> = 0 V to 3.6 V	-	-	±0.5	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-	±0.5	μA
ΔI <sub>OFF</sub>	additional power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V to 0.2 V	-	-	±0.6	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = GND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.9	μA
ΔI <sub>CC</sub>	additional supply current	per pin; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 3.3 V	[1] -	-	50	μA

**Table 7. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>T<sub>amb</sub> = -40 °C to +125 °C</b>						
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 0.8 V	0.75 × V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	0.70 × V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	-	-	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 0.8 V	-	-	0.25 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	-	-	0.30 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>				
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	V <sub>CC</sub> - 0.11	-	-	V
		I <sub>O</sub> = -1.1 mA; V <sub>CC</sub> = 1.1 V	0.6 × V <sub>CC</sub>	-	-	V
		I <sub>O</sub> = -1.7 mA; V <sub>CC</sub> = 1.4 V	0.93	-	-	V
		I <sub>O</sub> = -1.9 mA; V <sub>CC</sub> = 1.65 V	1.17	-	-	V
		I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 2.3 V	1.77	-	-	V
		I <sub>O</sub> = -3.1 mA; V <sub>CC</sub> = 2.3 V	1.67	-	-	V
		I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V	2.40	-	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>				
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.11	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	0.33 × V <sub>CC</sub>	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.41	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.39	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.36	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.50	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.36	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = GND to 3.6 V; V <sub>CC</sub> = 0 V to 3.6 V	-	-	±0.75	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-	±0.75	μA
ΔI <sub>OFF</sub>	additional power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V to 0.2 V	-	-	±0.75	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = GND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	1.4	μA
ΔI <sub>CC</sub>	additional supply current	per pin; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 3.3 V	[1]	-	75	μA

[1] One input at V<sub>CC</sub> - 0.6 V, other input at V<sub>CC</sub> or GND.

## 11. Dynamic characteristics

**Table 8. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 9](#)

Symbol	Parameter	Conditions	25 °C			-40 °C to +125 °C				Unit
			Min	Typ <sup>[1]</sup>	Max	Min (85 °C)	Max (85 °C)	Min (125 °C)	Max (125 °C)	
<b>C<sub>L</sub> = 5 pF</b>										
t <sub>pd</sub>	propagation delay	CP to Q; see <a href="#">Figure 7</a> <sup>[2]</sup>								
		V <sub>CC</sub> = 0.8 V	-	19.7	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	2.6	5.5	11.0	2.4	12.9	2.4	14.2	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	2.0	3.8	7.0	1.8	8.1	1.8	9.0	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.7	3.1	5.4	1.5	6.4	1.5	7.1	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.4	2.3	4.0	1.1	4.7	1.1	5.2	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.2	2.0	3.4	0.9	4.0	0.9	4.4	ns
f <sub>max</sub>	maximum frequency	CP; see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 0.8 V	-	53	-	-	-	-	-	MHz
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	203	-	170	-	170	-	MHz
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	347	-	310	-	300	-	MHz
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	435	-	400	-	390	-	MHz
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	550	-	490	-	480	-	MHz
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	619	-	550	-	510	-	MHz
<b>C<sub>L</sub> = 10 pF</b>										
t <sub>pd</sub>	propagation delay	CP to Q; see <a href="#">Figure 7</a> <sup>[2]</sup>								
		V <sub>CC</sub> = 0.8 V	-	23.1	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	3.1	6.3	12.3	2.8	14.4	2.8	15.9	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	2.5	4.4	8.1	2.2	9.5	2.2	10.5	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	2.1	3.6	6.3	1.9	7.5	1.9	8.3	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.8	2.8	4.7	1.5	5.6	1.5	6.2	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.7	2.5	4.1	1.3	4.5	1.3	5.0	ns
f <sub>max</sub>	maximum frequency	CP; see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 0.8 V	-	52	-	-	-	-	-	MHz
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	192	-	150	-	150	-	MHz
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	324	-	280	-	230	-	MHz
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	421	-	310	-	250	-	MHz
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	486	-	370	-	360	-	MHz
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	550	-	410	-	360	-	MHz



**Table 8. Dynamic characteristics ...continued**  
 Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 9](#)

Symbol	Parameter	Conditions	25 °C			-40 °C to +125 °C				Unit
			Min	Typ <sup>[1]</sup>	Max	Min (85 °C)	Max (85 °C)	Min (125 °C)	Max (125 °C)	
<b>C<sub>L</sub> = 15 pF</b>										
t <sub>pd</sub>	propagation delay	CP to Q; see <a href="#">Figure 7</a> <sup>[2]</sup>								
		V <sub>CC</sub> = 0.8 V	-	26.6	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	3.5	7.1	13.6	3.2	15.6	3.2	17.2	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	2.8	5.0	9.2	2.5	10.7	2.5	11.8	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	2.4	4.1	7.1	2.2	8.5	2.2	9.4	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	2.2	3.2	5.4	1.9	6.3	1.9	7.0	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	2.9	4.5	1.6	5.0	1.6	5.5	ns
f <sub>max</sub>	maximum frequency	CP; see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 0.8 V	-	50	-	-	-	-	-	MHz
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	181	-	120	-	120	-	MHz
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	301	-	190	-	160	-	MHz
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	407	-	240	-	190	-	MHz
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	422	-	300	-	270	-	MHz
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	481	-	320	-	300	-	MHz
<b>C<sub>L</sub> = 30 pF</b>										
t <sub>pd</sub>	propagation delay	CP to Q; see <a href="#">Figure 7</a> <sup>[2]</sup>								
		V <sub>CC</sub> = 0.8 V	-	36.8	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	4.7	9.3	17.3	4.2	23.3	4.2	25.6	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	3.8	6.4	11.8	3.3	14.3	3.3	15.7	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	3.3	5.3	9.4	3.0	11.3	3.0	12.4	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	3.0	4.3	7.0	2.7	8.5	2.7	9.4	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.8	3.9	5.8	2.6	7.2	2.6	7.9	ns
f <sub>max</sub>	maximum frequency	CP; see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 0.8 V	-	28	-	-	-	-	-	MHz
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	128	-	70	-	70	-	MHz
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	206	-	120	-	110	-	MHz
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	262	-	150	-	120	-	MHz
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	269	-	190	-	170	-	MHz
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	309	-	200	-	190	-	MHz

**Table 8. Dynamic characteristics ...continued**  
 Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 9](#)

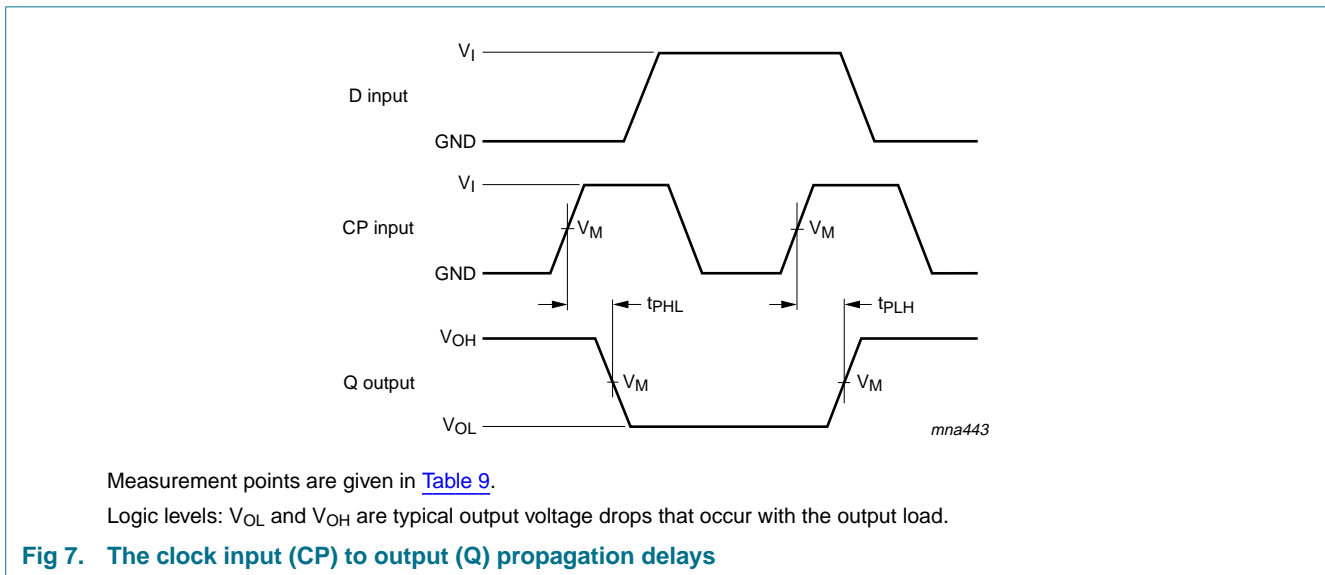
Symbol	Parameter	Conditions	25 °C			–40 °C to +125 °C				Unit
			Min	Typ <sup>[1]</sup>	Max	Min (85 °C)	Max (85 °C)	Min (125 °C)	Max (125 °C)	
<b>C<sub>L</sub> = 5 pF, 10 pF, 15 pF and 30 pF</b>										
t <sub>su</sub>	set-up time	HIGH; D to CP; see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 0.8 V	-	3.4	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	0.8	-	1.6	-	1.4	-	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	0.5	-	1.0	-	1.0	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	0.5	-	0.9	-	0.9	-	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	0.4	-	0.7	-	0.7	-	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	0.4	-	0.6	-	0.6	-	ns
		LOW; D to CP; see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 0.8 V	-	3.0	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	0.9	-	1.4	-	1.4	-	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	0.6	-	1.0	-	1.0	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	0.5	-	0.9	-	0.9	-	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	0.5	-	0.8	-	0.8	-	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	0.7	-	1.0	-	1.0	-	ns
t <sub>h</sub>	hold time	D to CP; see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 0.8 V	-	-1.9	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	-0.6	-	0.2	-	0.2	-	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	-0.4	-	0	-	0	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	-0.4	-	0	-	0	-	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-0.4	-	0	-	0	-	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-0.3	-	0	-	0	-	ns
t <sub>w</sub>	pulse width	HIGH or LOW; CP; see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 0.8 V	-	5.6	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	2.4	-	3.5	-	3.5	-	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	1.3	-	2.0	-	2.0	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	0.9	-	1.9	-	1.9	-	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	0.7	-	2.0	-	2.0	-	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	0.6	-	2.2	-	2.2	-	ns

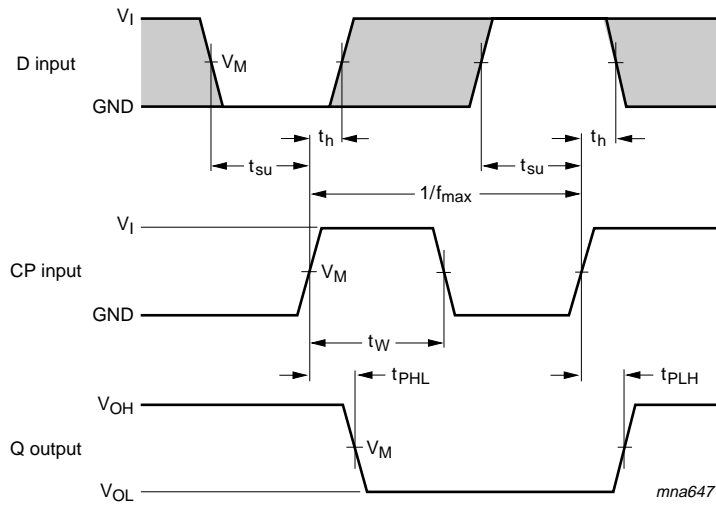
**Table 8. Dynamic characteristics ...continued**  
 Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 9](#)

Symbol	Parameter	Conditions	25 °C			-40 °C to +125 °C				Unit
			Min	Typ <sup>[1]</sup>	Max	Min (85 °C)	Max (85 °C)	Min (125 °C)	Max (125 °C)	
C <sub>PD</sub>	power dissipation capacitance	f <sub>i</sub> = 1 MHz; V <sub>I</sub> = GND to V <sub>CC</sub> <sup>[3]</sup>								
		V <sub>CC</sub> = 0.8 V	-	1.6	-	-	-	-	-	pF
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	1.7	-	-	-	-	-	pF
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	1.8	-	-	-	-	-	pF
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	1.9	-	-	-	-	-	pF
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	2.3	-	-	-	-	-	pF
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	2.7	-	-	-	-	pF	

- [1] All typical values are measured at nominal V<sub>CC</sub>.
- [2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.
- [3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where:  
 f<sub>i</sub> = input frequency in MHz;  
 f<sub>o</sub> = output frequency in MHz;  
 C<sub>L</sub> = output load capacitance in pF;  
 V<sub>CC</sub> = supply voltage in V;  
 N = number of inputs switching;  
 $\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.

## 12. Waveforms





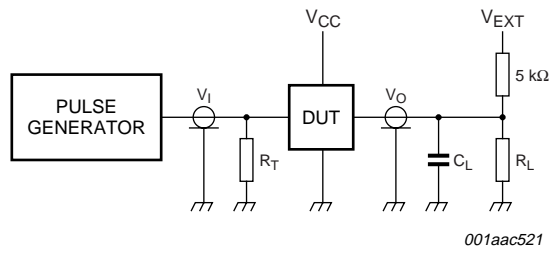
Measurement points are given in [Table 9](#).

Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage drops that occur with the output load.

**Fig 8.** The clock input (CP) to output (Q) propagation delays, CP clock pulse width, D to CP setup times, CP to D hold times and the CP maximum frequency

**Table 9.** Measurement points

Supply voltage	Output	Input		
$V_{CC}$	$V_M$	$V_M$	$V_I$	$t_r = t_f$
0.8 V to 3.6 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{CC}$	$\leq 3.0$ ns



Test data is given in [Table 10](#).

Definitions for test circuit:

$R_L$  = Load resistance.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

$V_{EXT}$  = External voltage for measuring switching times.

**Fig 9. Load circuitry for switching times**

**Table 10. Test data**

Supply voltage	Load		$V_{EXT}$		
$V_{CC}$	$C_L$	$R_L$ [1]	$t_{PLH}, t_{PHL}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 kΩ or 1 MΩ	open	GND	$2 \times V_{CC}$

[1] For measuring enable and disable times  $R_L = 5 \text{ k}\Omega$ , for measuring propagation delays, setup and hold times and pulse width  $R_L = 1 \text{ M}\Omega$ .

13. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1

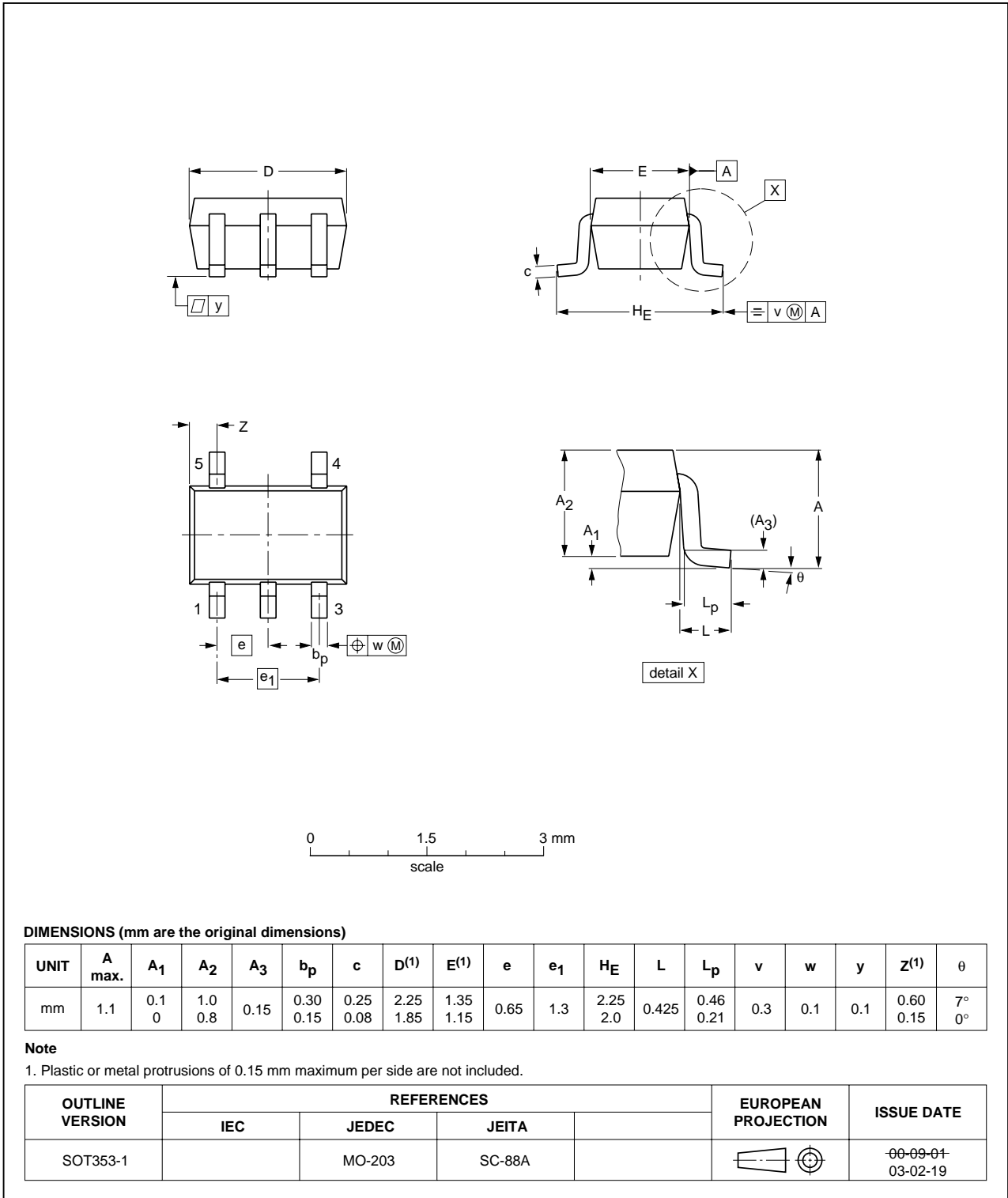


Fig 10. Package outline SOT353-1 (TSSOP5)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

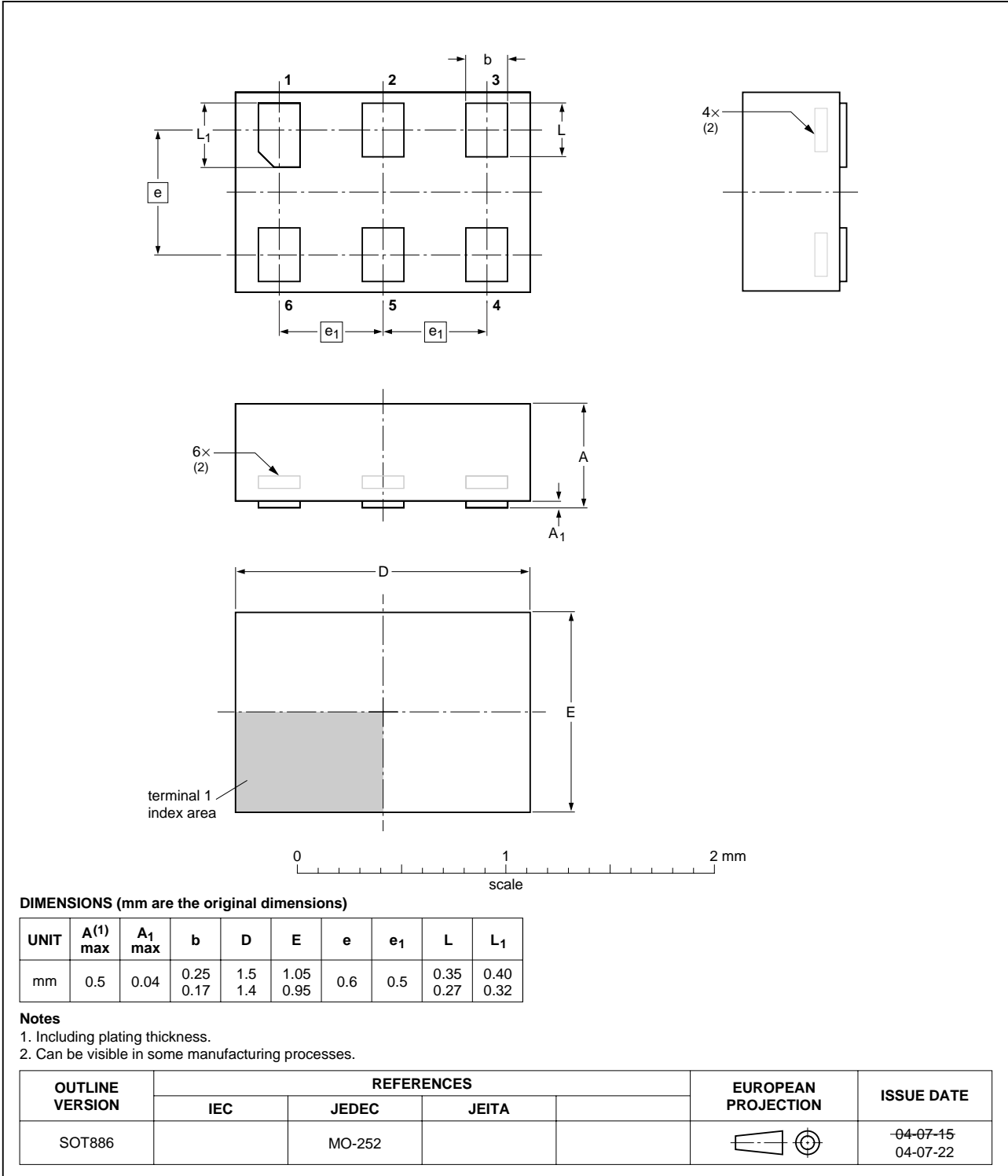


Fig 11. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm

SOT891

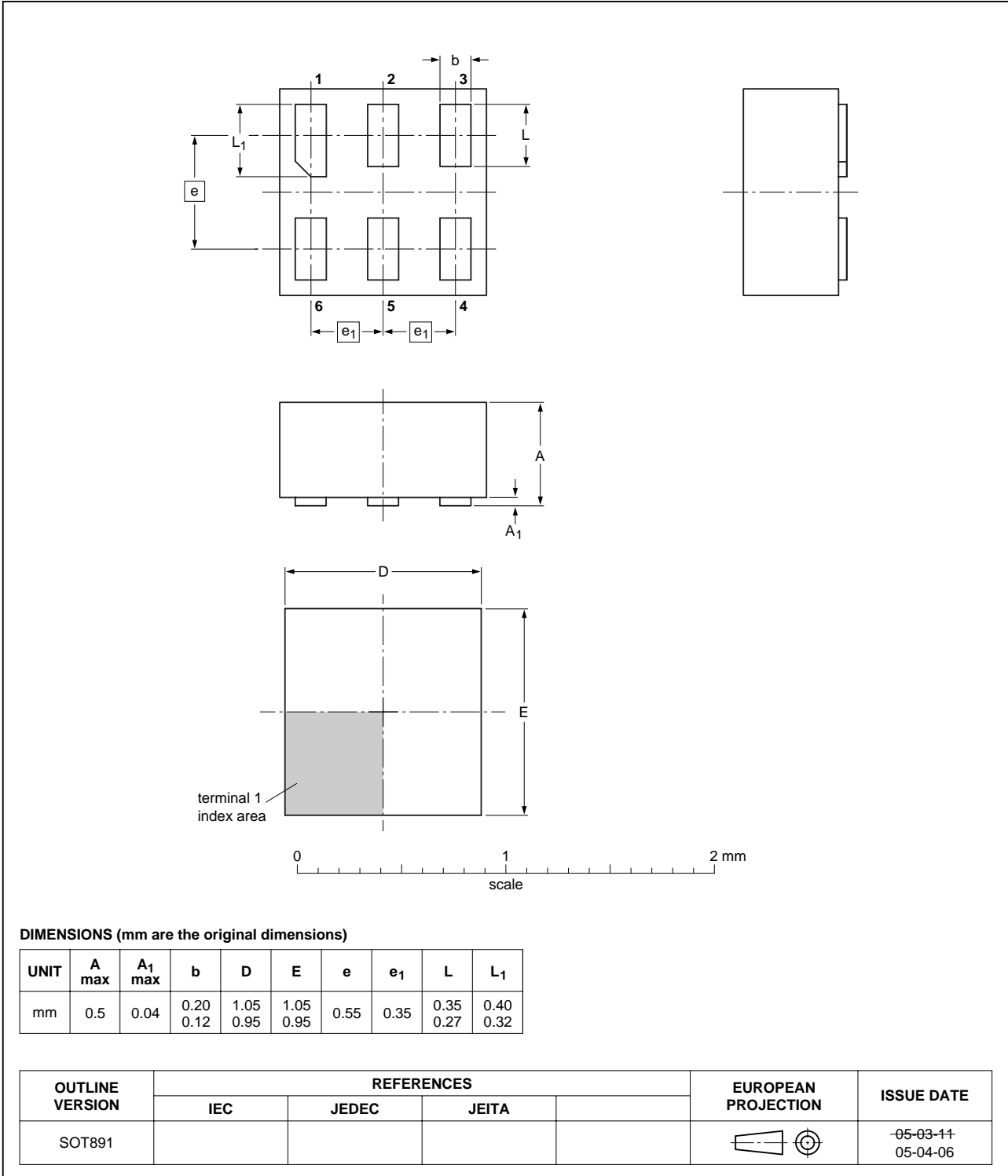


Fig 12. Package outline SOT891 (XSON6)



## 14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AUP1G79_2	20061017	Product data sheet	-	74AUP1G79_1
Modifications:	<ul style="list-style-type: none"> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li>ESD HBM and <math>C_{PD}</math> values modified in <a href="#">Section 2, Table 8</a>.</li> <li>Added type number 74AUP1G79GF (XSON6/SOT891) package.</li> </ul>			
74AUP1G79_1	20050912	Product data sheet	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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